

FDG6335N

20V N-Channel PowerTrench® MOSFET

General Description

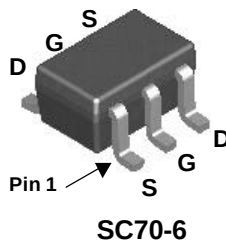
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized use in small switching regulators, providing an extremely low $R_{DS(ON)}$ and gate charge (Q_G) in a small package.

Applications

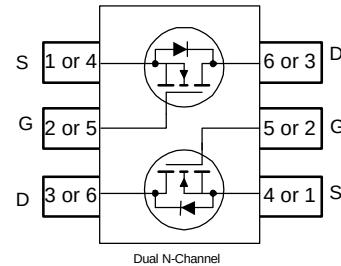
- DC/DC converter
- Power management
- Loadswitch

Features

- 0.7 A, 20 V. $R_{DS(ON)} = 300\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
 $R_{DS(ON)} = 400\text{ m}\Omega @ V_{GS} = 2.5\text{ V}$
- Low gate charge (1.1 nC typical)
- High performance trench technology for extremely low $R_{DS(ON)}$
- Compact industry standard SC70-6 surface mount package



The pinouts are symmetrical; pin 1 and pin 4 are interchangeable.



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous (Note 1)	0.7	A
	– Pulsed	2.1	
P_D	Power Dissipation for Single Operation (Note 1)	0.3	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to $+150$	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	415	$^\circ\text{C/W}$
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Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.35	FDG6335N	7"	8mm	3000 units

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain–Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		14		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 16 V, V _{GS} = 0 V			1	μA
I _{GSSF}	Gate–Body Leakage, Forward	V _{GS} = 12 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate–Body Leakage, Reverse	V _{GS} = −12 V, V _{DS} = 0 V			−100	nA
On Characteristics (Note 2)						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	0.6	1.1	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I _D = −250 μA, Referenced to 25°C		−2.8		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	V _{GS} = 4.5 V, I _D = 0.7 A V _{GS} = 2.5 V, I _D = 0.6 A V _{GS} = 4.5 V, I _D = 0.7 A, T _J =125°C		180 293 247	300 400 442	mΩ
I _{D(on)}	On–State Drain Current	V _{GS} = 4.5 V, V _{DS} = 5 V	1			A
g _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 0.7 A		2.8		S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 10 V, V _{GS} = 0 V, f = 1.0 MHz		113		pF
C _{oss}	Output Capacitance			34		pF
C _{rss}	Reverse Transfer Capacitance			16		pF
Switching Characteristics (Note 2)						
t _{d(on)}	Turn–On Delay Time	V _{DD} = 10 V, I _D = 1 A, V _{GS} = 4.5 V, R _{GEN} = 6 Ω		5	10	ns
t _r	Turn–On Rise Time			7	15	ns
t _{d(off)}	Turn–Off Delay Time			9	18	ns
t _f	Turn–Off Fall Time			1.5	3	ns
Q _g	Total Gate Charge	V _{DS} = 10 V, I _D = 0.7 A, V _{GS} = 4.5 V		1.1	1.4	nC
Q _{gs}	Gate–Source Charge			0.24		nC
Q _{gd}	Gate–Drain Charge			0.3		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain–Source Diode Forward Current				0.25	A
V _{SD}	Drain–Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0.25 A (Note 2)		0.74	1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. $R_{\theta JA} = 415^\circ\text{C/W}$ when mounted on a minimum pad.

2. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%

Typical Characteristics

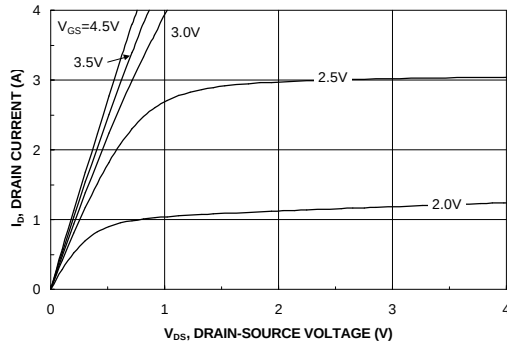


Figure 1. On-Region Characteristics.

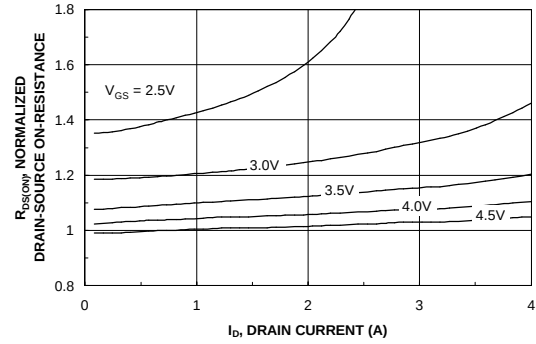


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

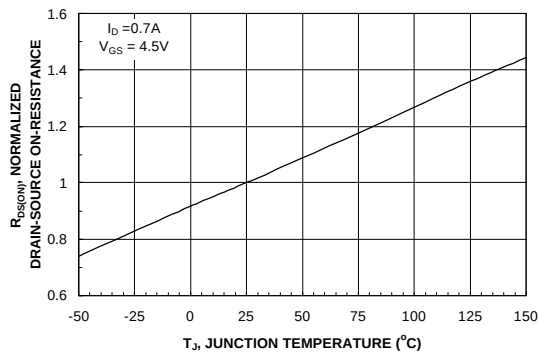


Figure 3. On-Resistance Variation with Temperature.

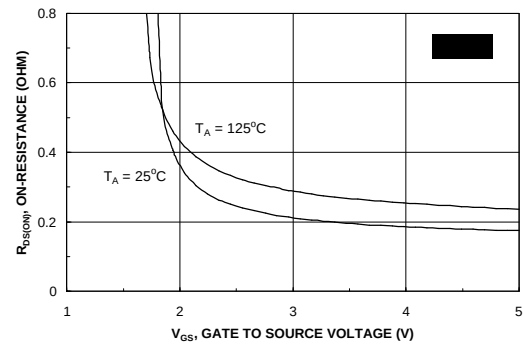


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

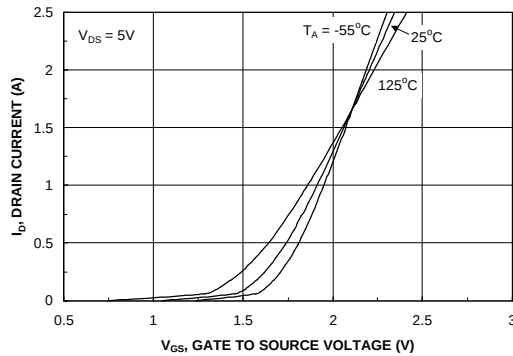


Figure 5. Transfer Characteristics.

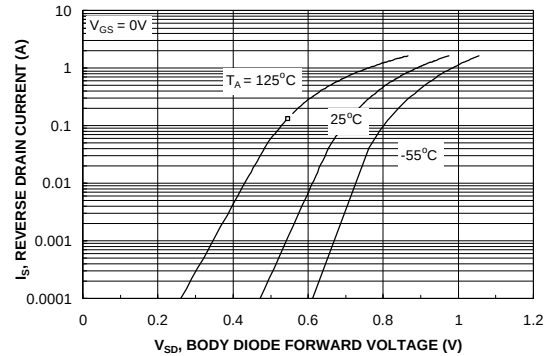


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

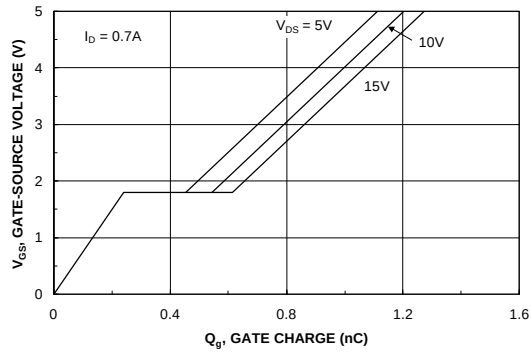


Figure 7. Gate Charge Characteristics.

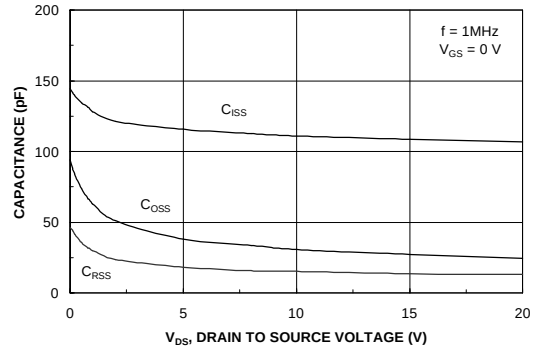


Figure 8. Capacitance Characteristics.

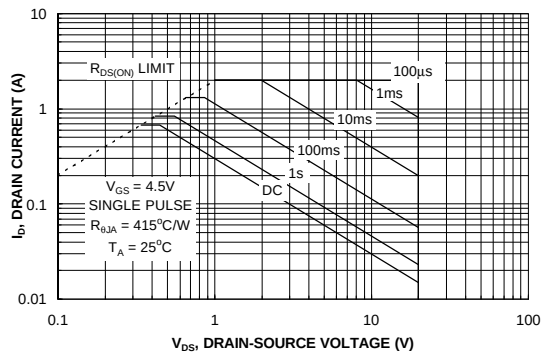


Figure 9. Maximum Safe Operating Area.

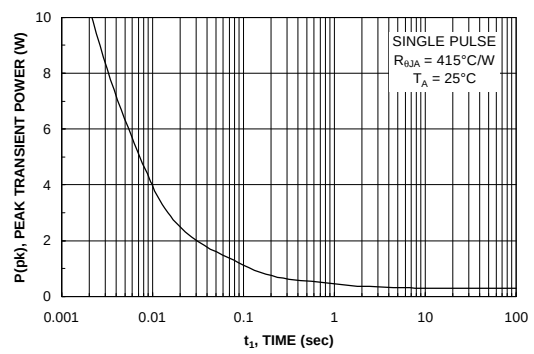


Figure 10. Single Pulse Maximum Power Dissipation.

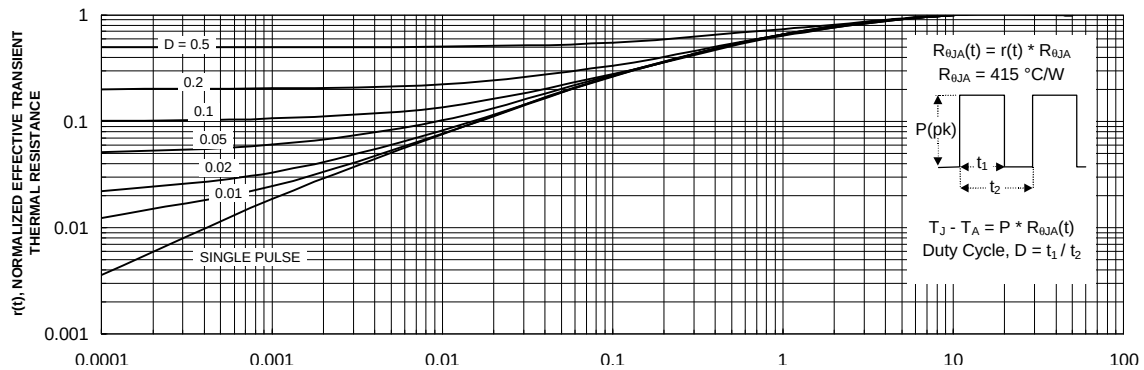


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1.
Transient thermal response will change depending on the circuit board design.

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